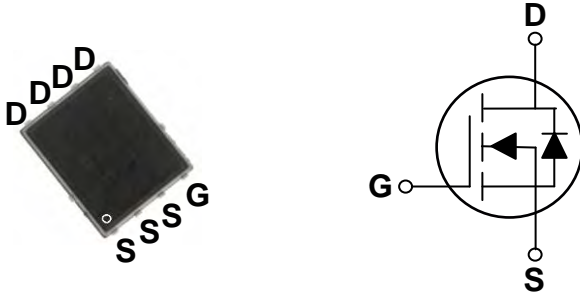


## 60V N-Channel MOSFETs

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK5X6 Pin Configuration



BVDSS	RDSON	ID
60V	21 mΩ	40A

### Features

- 60V, 40A, RDS(ON) =21mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting

### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>C</sub> =25°C)	40	A
	Drain Current – Continuous (T <sub>C</sub> =100°C)	25	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	160	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	42	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	29	A
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> =25°C)	83	W
	Power Dissipation – Derate above 25°C	0.66	W/°C
T <sub>STG</sub>	Storage Temperature Range	-50 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	1.5	°C/W



# FTK6906DFN56

## 60V N-Channel MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.07	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=15A$	---	17	21	m $\Omega$
		$V_{GS}=4.5V, I_D=8A$	---	20	24	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=25\mu A$	1.2	1.8	2.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	5	---	mV/ $^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=10V, I_D=10A$	---	9	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{DS}=30V, V_{GS}=10V, I_D=15A$	---	28	42	nC
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>		---	3.5	7	
$Q_{gd}$	Gate-Drain Charge <sup>2,3</sup>		---	6.5	10	
$T_{d(on)}$	Turn-On Delay Time <sup>2,3</sup>	$V_{DD}=30V, V_{GS}=10V, R_G=6\Omega$ $I_D=-1A$	---	7.2	14	ns
$T_r$	Rise Time <sup>2,3</sup>		---	38	72	
$T_{d(off)}$	Turn-Off Delay Time <sup>2,3</sup>		---	34	65	
$T_f$	Fall Time <sup>2,3</sup>		---	8.2	16	
$C_{iss}$	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, F=1\text{MHz}$	---	1680	2440	pF
$C_{oss}$	Output Capacitance		---	115	170	
$C_{riss}$	Reverse Transfer Capacitance		---	85	125	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	---	2.2	4.4	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	40	A
$I_{SM}$	Pulsed Source Current		---	---	160	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$V_{GS}=0V, I_S=-1A, dI/dt=100A/\mu s$	---	19.6	---	ns
$Q_{rr}$	Reverse Recovery Charge <sup>2</sup>	$T_J=25^\circ\text{C}$	---	14.2	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=29A, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## Typical Performance Characteristics

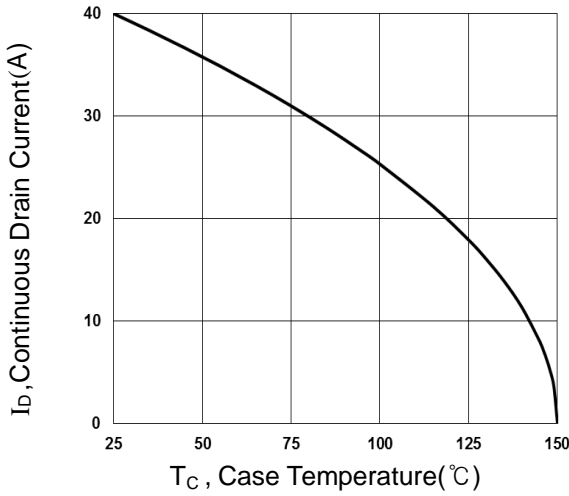


Fig.1 Continuous Drain Current vs.  $T_C$

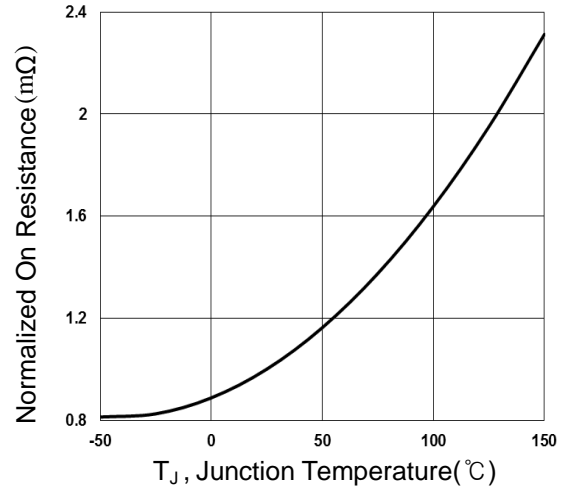


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

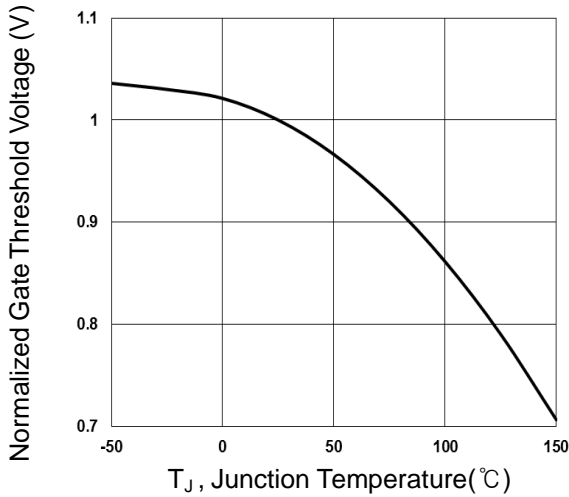


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

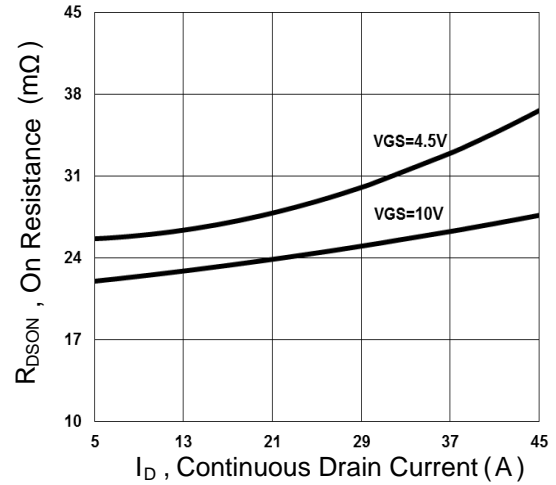


Fig.4  $R_{DS(on)}$  vs. Continuous Drain Current

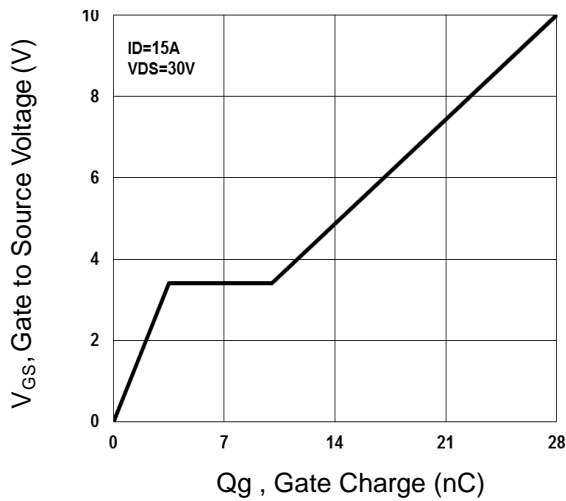


Fig.5 Gate Charge Waveform

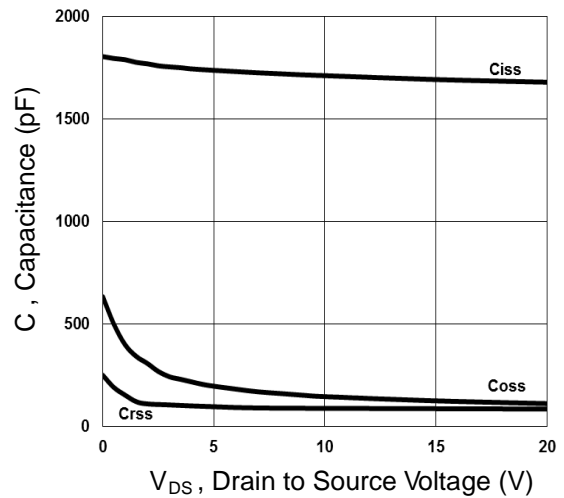
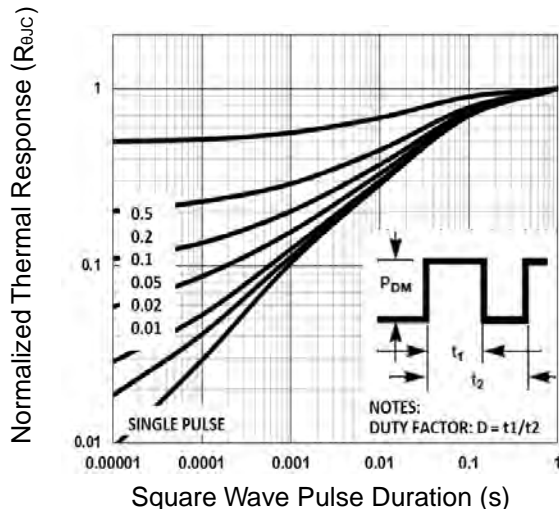
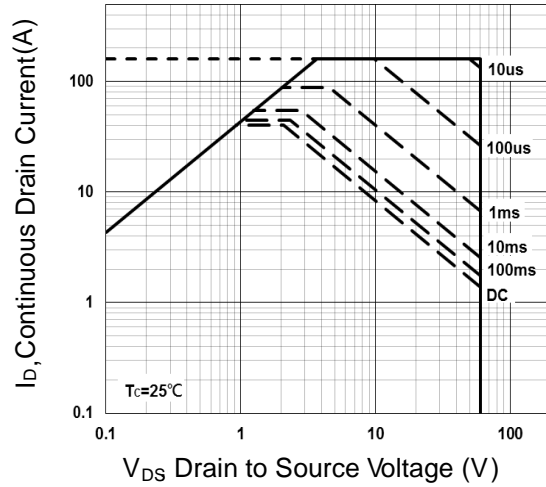


Fig.6 Capacitance Characteristics

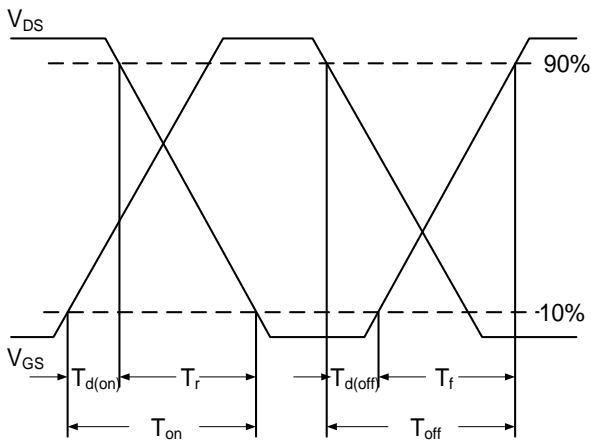
## Typical Performance Characteristics(Con.)



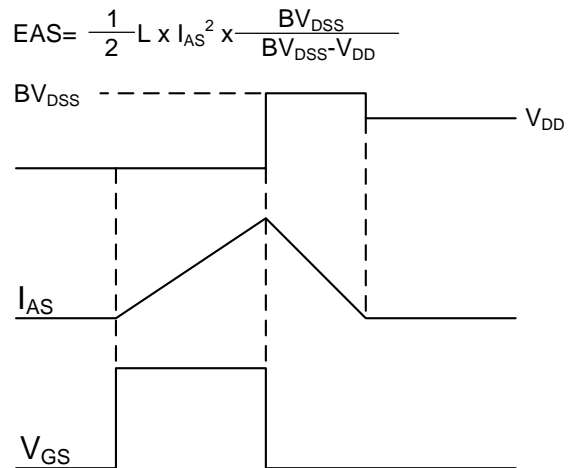
**Fig. 7 Normalized Transient Impedance**



**Fig. 8 Maximum Safe Operation Area**

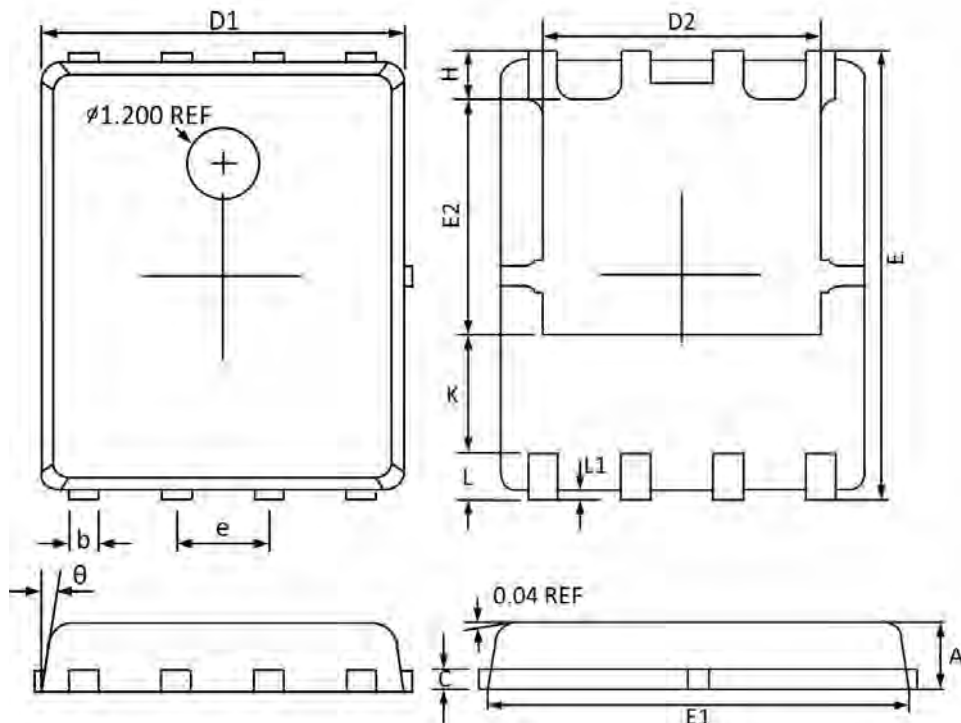


**Fig. 9 Switching Time Waveform**



**Fig. 10 EAS Waveform**

## PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
$\theta$	12°	0°	12°	0°